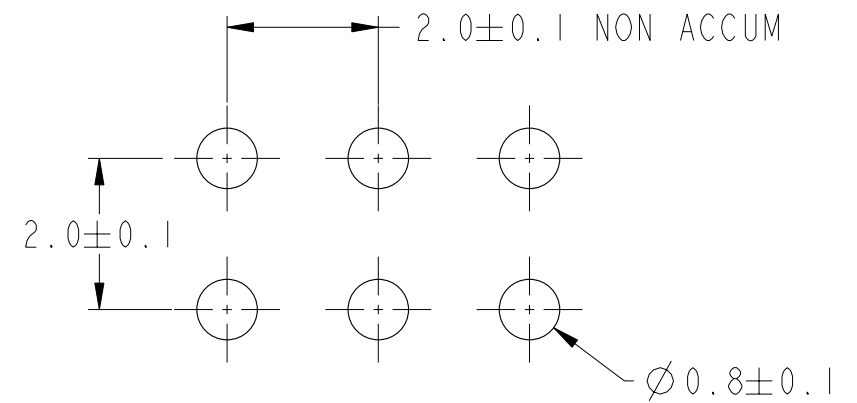
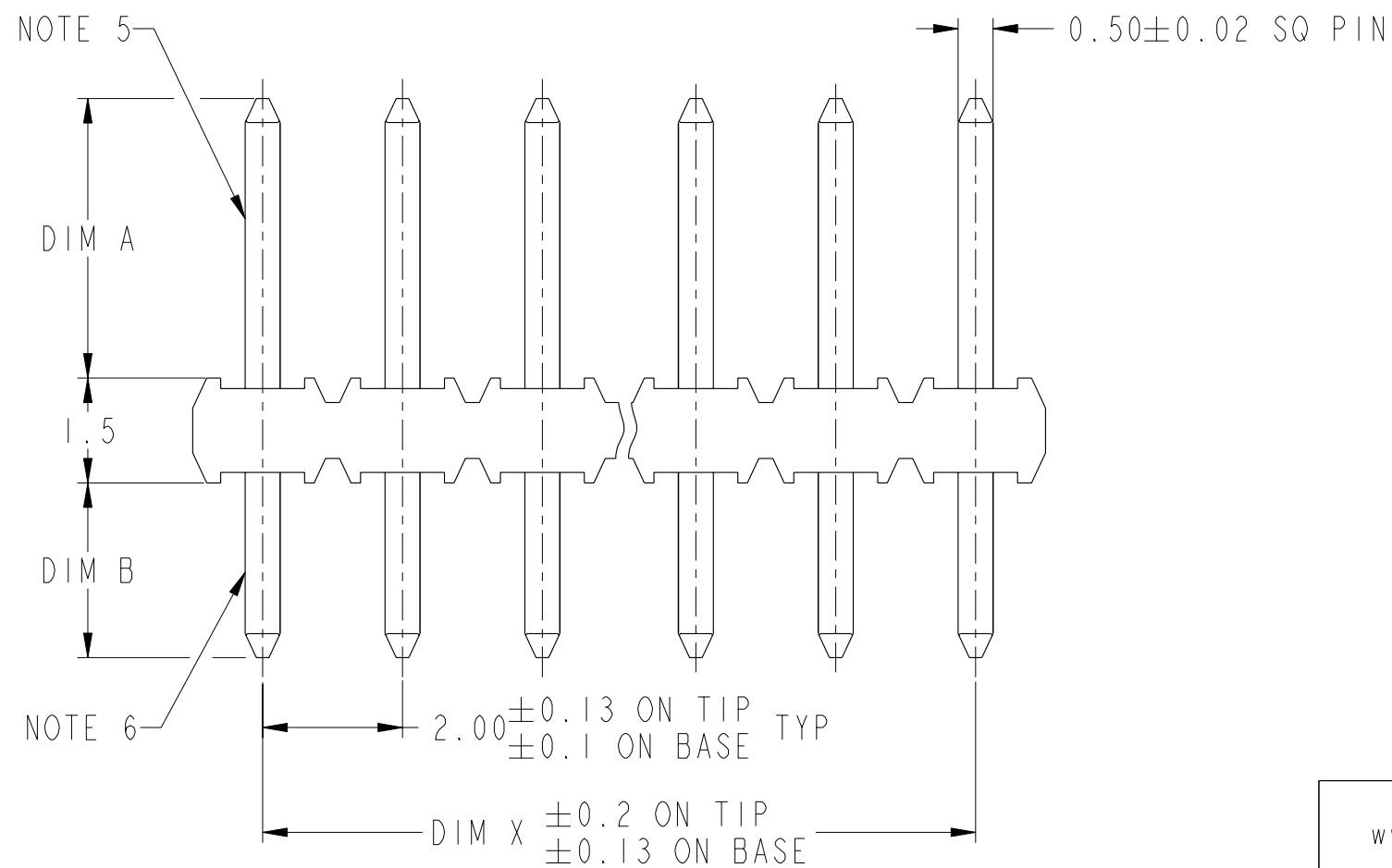
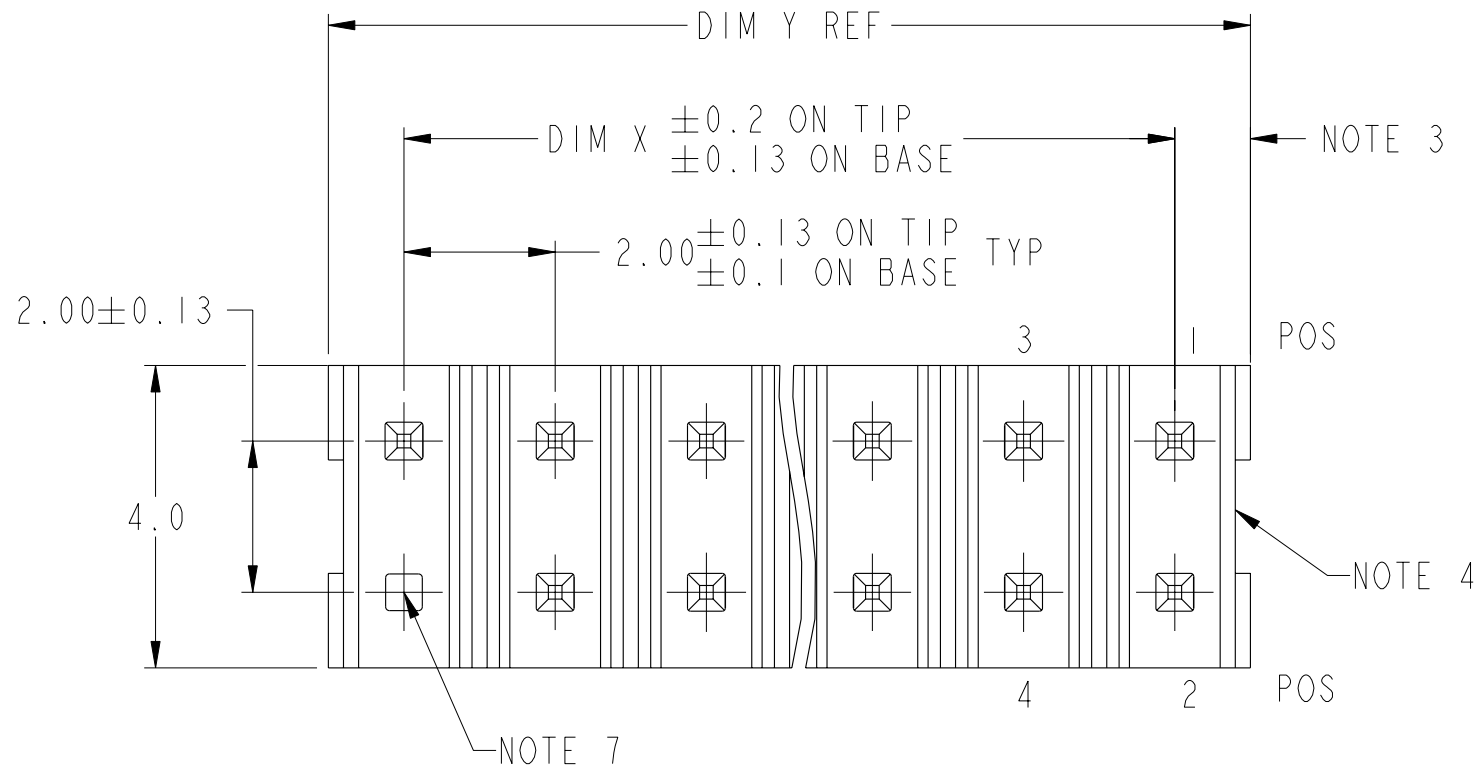


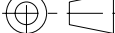
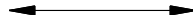


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RECOMMENDED MOUNTING HOLE LAYOUT

rev	ecn no	dr	date
E	S20042	JPEH	2002/04/23
F	S04-0172	JPEH	2004/08/11
G	S04-0224	KBM	2004/10/25
H	S05-0060	KBM	2005/02/28
J	S06-0236	KHL	2005/02/28
K	S10-0205	PR	2009/12/16
-	-	-	-

www.fciconnect.com			surface ISO 1302		- ✓	tolerance std ISO 406 ISO 1101		projection 	MM 	
			TOLERANCES UNLESS OTHERWISE SPECIFIED							
Dr	JPEH	2002/04/23	ANGULAR	LINEAR	0.X	±-	size A3	Scale 10:1		
Eng	JPEH	2004/08/31			0.XX	±0.25				
Chr	KH LEE	2009/12/16			0° ±3°	0.XXX		±-	ECN	S10-0205
Appr	JOEY NG	2009/12/16	Product family				MINITEK	Spec ref -		
			title POL. MINITEK II STR HEADER (DUPLEX)				dwg no 61641		Rev. K	
			catalog no -				CUSTOMER		sheet 1 of 2	

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A

B

C

D

PRODUCT NO. SEE NOTE 8	POS	DIM A	DIM B	POL. POS	DIM X	DIM Y
61641-X01	2X3	4.0	2.5	3	4	6
-X02	2X22	4.0	2.5	20	42	44
-X03	2X13	4.0	2.5	26	24	26
-X04	2X13	5.27	3.77	26	24	26
-X05	2X16	4.0	2.5	3, 4, 5, 6, 32	30	32

NOTES:

- MATERIAL:
BODY : HIGH TEMPERATURE THERMOPLASTIC UL 94V-0 BLACK
PIN : COPPER ALLOY
- TOLERANCE UNLESS OTHERWISE NOTED ± 0.25
- DIM 1.0 ± 0.15 MOLDED SIDE(S) ONLY. IF SIDE(S) ARE BROKEN.
DIM 1.5 MAX APPLIES.
- RECESS APPLIES TO MOLDED SIDE(S) ONLY.
- PLATING ON MATING LENGTH:
-3YY --- 0.38 μ m Au OVER 1.27 μ m MIN NICKEL UNDERPLATE.
-5YY --- 0.38 μ m PdNi WITH Au FLASH OVER 1.27 μ m MIN NICKEL UNDERPLATE.
-6YY --- 0.76 μ m PdNi WITH Au FLASH OVER 1.27 μ m MIN NICKEL UNDERPLATE.
- SOLDER TAIL PLATING:
a) SOLDER TAIL OF P/N:61641-XXX IS 3.81 μ m MIN TIN/LEAD (90/10) PLATED
OVER 1.27 μ m MIN NICKEL UNDERPLATE.
b) SOLDER TAIL OF P/N:61641-XXXLF IS 2.54 μ m MIN TIN PLATED
OVER 1.27 μ m MIN NICKEL UNDERPLATE (LEADFREE).
- POLARISED BY OMISSION OF PINS. REFER TO TABLE
FOR POL. POS.

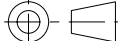
8. PART NUMBER INFORMATION

61641-XY YLF



- THE HOUSING WILL WITHSTAND EXPOSURE TO 255°C
PEAK TEMPERATURE FOR 10 SECONDS IN A CONVECTION, INFRA-RED
OR VAPOR PHASE REFLOW OVEN.
- THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C
PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER
APPLICATION WITH A 1.57MM MINIMUM THICK CIRCUIT BOARD.
- THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND
OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008.
- A $\triangle K$ SYMBOL WILL BE NEXT TO ANY DIMENSION, VIEW OR NOTE
WHICH HAS BEEN MODIFIED WITH THE CURRENT DRAWING REVISION.

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www.fciconnect.com			surface - ✓ ISO 1302		tolerance std ISO 406 ISO 1101		projection 		MM 		
			TOLERANCES UNLESS OTHERWISE SPECIFIED								
Dr	JPEH	2002/04/23	ANGULAR	LINEAR	0.X	±-	size A3	Scale 10:1			
Eng	JPEH	2004/08/31			0.XX	±0.25					
Chr	KH LEE	2009/12/16			0° ±3°	0.XXX					±-
Appr	JOEY NG	2009/12/16	Product family				MINITEK	Spec ref			
		title POL. MINITEK II STR HEADER (DUPLEX)				dwg no 61641				Rev K	
		catalog no				-	CUSTOMER			sheet 2 of 2	